

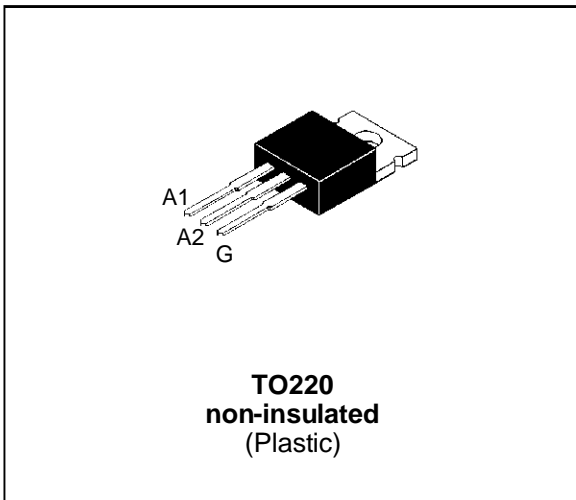
## STANDARD TRIACS

### FEATURES

- $I_{T(RMS)} = 10A$
- $V_{DRM} = 400V$  to  $800V$
- High surge current capability

### DESCRIPTION

The T10xxxH series of triacs uses a high performance MESA GLASS technology. These parts are intended for general purpose switching and phase control applications.



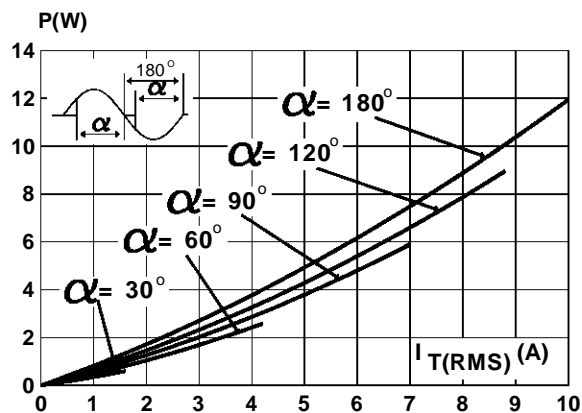
### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
$I_{T(RMS)}$	RMS on-state current (360° conduction angle)	$T_c = 95\text{ }^\circ\text{C}$ 10	A
$I_{TSM}$	Non repetitive surge peak on-state current ( $T_j$ initial = $25\text{ }^\circ\text{C}$ )	$t_p = 8.3\text{ ms}$	105
		$t_p = 10\text{ ms}$	100
$I^2t$	$I^2t$ Value for fusing	$t_p = 10\text{ ms}$ 50	$A^2s$
$di/dt$	Critical rate of rise of on-state current $I_G = 500\text{ mA}$ $di_G/dt = 1\text{ A}/\mu\text{s}$ .	Repetitive $F = 50\text{ Hz}$	10
		Non Repetitive	50
$T_{stg}$ $T_j$	Storage and operating junction temperature range	- 40, + 150 - 40, + 125	$^\circ\text{C}$
TI	Maximum lead temperature for soldering during 10s at 4.5mm from case	260	$^\circ\text{C}$

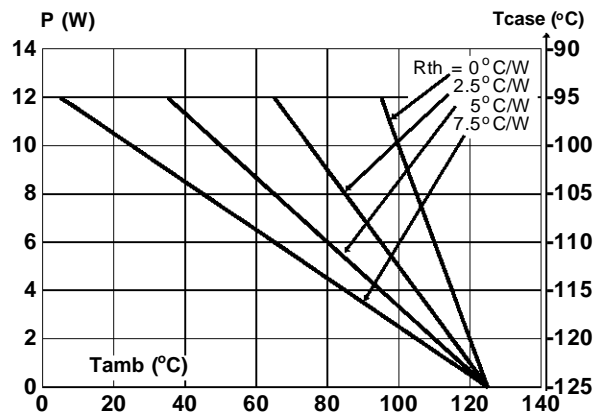
Symbol	Parameter	Voltage				Unit
		D	M	S	N	
$V_{DRM}$ $V_{RRM}$	Repetitive peak off-state voltage $T_j = 125\text{ }^\circ\text{C}$	400	600	700	800	V



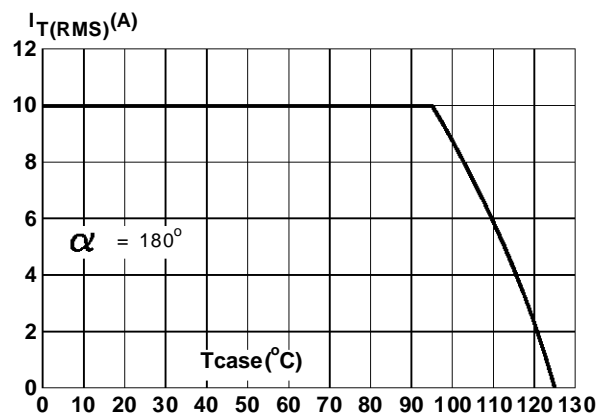
**Fig.1 :** Maximum RMS power dissipation versus RMS on-state current.



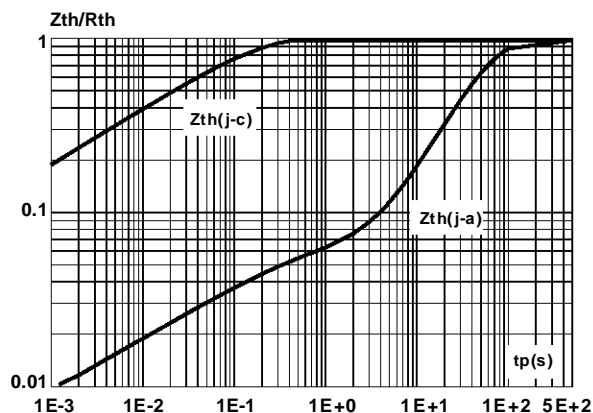
**Fig.2 :** Correlation between maximum RMS power dissipation and maximum allowable temperature (Tamb and Tcase) for different thermal resistances heatsink + contact.



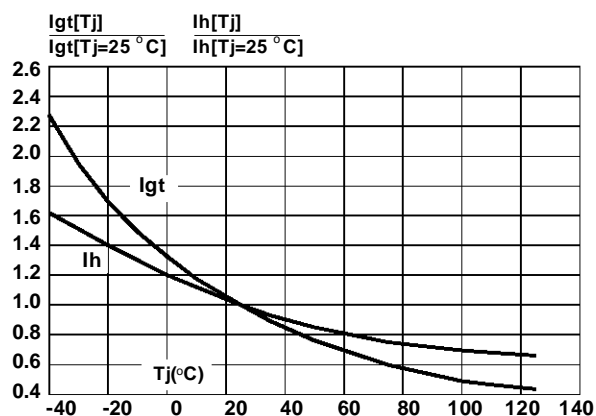
**Fig.3 :** RMS on-state current versus case temperature.



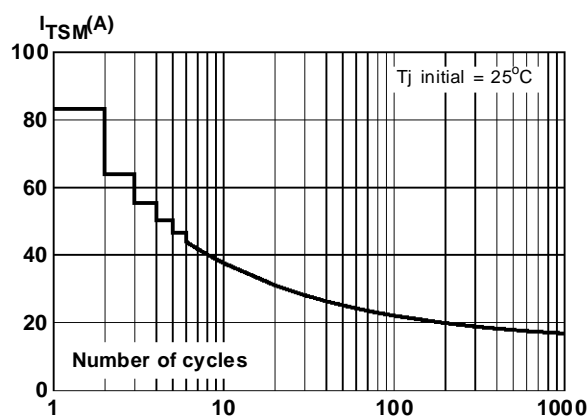
**Fig.4 :** Relative variation of thermal impedance versus pulse duration.



**Fig.5 :** Relative variation of gate trigger current and holding current versus junction temperature.

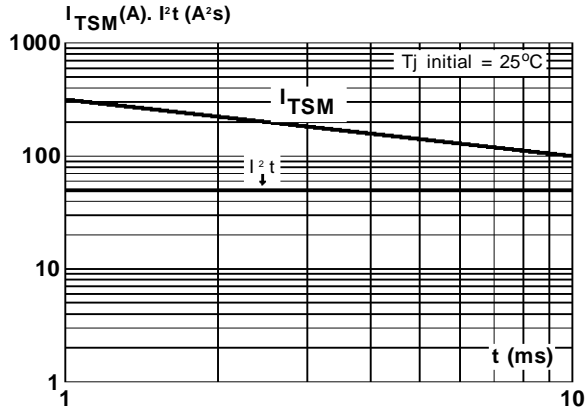


**Fig.6 :** Non repetitive surge peak on-state current versus number of cycles.

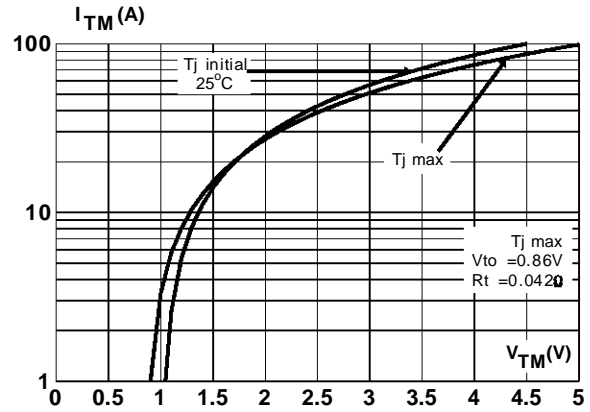


# T10xxxH

**Fig.7 :** Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \leq 10\text{ms}$ , and corresponding value of  $I^2t$ .



**Fig.8 :** On-state characteristics (maximum values).



**PACKAGE MECHANICAL DATA**  
 TO220 Non-insulated (Plastic)

REF.	DIMENSIONS					
	Millimeters			Inches		
	Typ.	Min.	Max.	Typ.	Min.	Max.
A			10.3			0.406
B		6.3	6.5	0.248	0.256	
C			9.1			0.358
D		12.7			0.500	
F			4.2			0.165
G			3.0			0.118
H		4.5	4.7		0.177	0.185
I		3.53	3.66		0.139	0.144
J		1.2	1.3		0.047	0.051
L			0.9			0.035
M	2.7			0.106		
N			5.3			0.209
N1	2.54			0.100		
O		1.2	1.4		0.047	0.055
P			1.15			0.045

Marking : type number  
 Weight : 1.8 g

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